



SLOVENSKI STANDARD
SIST EN 62326-1:2001
01-marec-2001

Printed boards - Part 1: Generic specification

Printed boards -- Part 1: Generic specification

Leiterplatten -- Teil 1: Fachgrundspezifikation

Cartes imprimées -- Partie 1: Spécification générique

Ta slovenski standard je istoveten z: EN 62326-1:1997

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ICS:

31.180 Printed circuits and boards

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en

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EUROPEAN STANDARD

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NORME EUROPÉENNE

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January 1997

ICS 31.180

Descriptors: Printed board, generic specification, particular stipulations, quality assessment, capability approval, preparation of detail specifications

English version

Printed boards
Part 1: Generic specification
(IEC 2326-1:1996)

Cartes imprimées
Partie 1: Spécification générique
(CEI 2326-1:1996)

Leiterplatten
Teil 1: Fachgrundspezifikation
(IEC 2326-1:1996)

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This European Standard was approved by CENELEC on 1996-12-09. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 52/654/FDIS, future edition 1 of IEC 2326-1, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62326-1 on 1996-12-09.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 1997-09-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) -

Annexes designated "normative" are part of the body of the standard.
Annexes designated "informative" are given for information only.
In this standard, annex ZA is normative and annexes A to E are informative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 2326-1:1996 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications
with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 1189-3	¹⁾	Test methods for electrical materials, interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)	-	-
IEC 1182-1	1994	Printed boards - Electronic data description and transfer Part 1: Printed board description in digital form	-	-
QC 001002	1986	Rules of procedure of the IEC Quality Assessment System for Electronic Components (IECQ)	-	-
QC 001005	1994	Register of Firms, Products and Services approved under the IECQ System, including ISO 9000	-	-
ISO 9000	series	Quality management and quality assurance standards	EN ISO 9000	series
ISO 9001	1994	Quality systems - Model for quality assurance in design development, production, installation and servicing	EN ISO 9001	1994
ISO 9002	1994	Quality systems - Model for quality assurance in production, installation and servicing	EN ISO 9002	1994

1) At present under IEC-CENELEC parallel vote (52/627/FDIS).

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Partie 1:
Spécification générique

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Printed boards –
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Part 1:
Generic specification

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Международная Электротехническая Комиссия

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• Pour prix, voir catalogue en vigueur
For price, see current catalogue

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARDS -

Part 1: Generic specification

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
- 5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 2326-1 has been prepared by IEC technical committee 52: Printed circuits.

This standard cancels and replaces IEC 326-1.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/654/FDIS	52/671/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Annexes A, B, C, D and E are for information only.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components.

INTRODUCTION

IEC 2326 is applicable to printed boards, irrespective of their method of manufacture, when they are ready for the mounting of components.

IEC 2326 is composed of separate parts covering information for the designer, generic, sectional and capability detail specifications for IEC Quality assessment system specification for test methods and requirements for the various types of printed boards.

IECQ is the Quality Assessment System for Electronic Components. It is a third party certification system. Its rules (including a description of the role of the inspectorates) are published in the following publications:

- QC 001001: 1986, *Basic Rules*
- QC 001002: 1986, *Rules of Procedure*.

This document contains the Generic Specification for printed boards of assessed quality and forms part of the Sectional Specifications and Capability Detail Specifications circulated to the National Committees.

For example:

For rigid multilayer printed board the following documents apply:

IEC 2326-1: 1996, *Printed boards – Part 1: Generic specification*

IEC 2326-4: 1996, *Printed boards – Part 4: Rigid multilayer printed boards with interlayer connections – Sectional specification*

IEC 2326-4-1: 1996, *Printed boards – Part 4: Rigid multilayer printed boards with interlayer connections – Section 1: Capability Detail Specification – Performance Levels A, B and C*

All three documents should be considered jointly.

For further information regarding specification structure and interrelationship between the specifications see annex B of this Generic Specification.

PRINTED BOARDS –

Part 1: Generic specification

1 Scope

This part of IEC 2326 is a Generic Specification (GS) applying to printed boards within the IEC quality assessment system for electronic components (IECQ). It relates to printed boards irrespective of their method of manufacture, when they are ready for mounting of components. This standard specifies the system and procedure for approval of manufacturers and products, and provides rules for the preparation of specifications for printed boards.

NOTE – Plated-through holes. Conductive holes may be achieved by plating-through, by other metallization techniques or by deposition of conductive polymeric materials. Requirements for non-plated-through conductive holes are under consideration

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 2326. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 2326 are encouraged to investigate the possibility of applying the most recent editions of the normative documents listed below. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC/FDIS 1189-3: *Test methods for electrical materials, interconnection structures and assemblies – Part 3: Test methods for interconnection structures*¹⁾

IEC 1182-1: 1994, *Printed boards – Electronic data description and transfer – Part 1: Printed board description in digital form*

QC 001002: 1986, *Rules of procedure of the IEC Quality Assessment System for electronic components (IECQ)*

QC 001005: 1994, *Register of Firms, Products and Services approved under the IECQ system, including ISO 9000*

ISO 9000, *Quality management and quality assurance standards*

ISO 9001: 1994, *Quality systems – Model for quality assurance in design development, production, installation and servicing*

ISO 9002: 1994, *Quality systems – Model for quality assurance in production, installation and servicing*

¹⁾ At present at the stage of Final Draft International Standard.